



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SAKAI et al.

Serial No.: 09/925,021

Filed: 8/9/2001

Title: SEMICONDUCTOR DYNAMIC
QUANTITY SENSOR WITH MOVABLE
ELECTRODE AND FIXED ELECTRODE
SUPPORTED BY SUPPORT SUBSTRATE

Atty. Dkt.: 01-186-RCE2

Art Unit: 2856

Examiner: Chapman

Commissioner for Patents
United States Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

DECLARATION UNDER 37 CFR 1.132

Sir:

I, Minekazu Sakai, declare as follows:

1. I am a named inventor, along with Yoshiyuki Kato and Minoru Murata, in the present application.

2. I am also a named inventor, along with Minoru Murata, Seiki Aoyama, and Youko Nakagawa, in U.S. Patent No. 6,450,031 (the '031 patent), which was filed as a U.S. patent application on July 26, 2000 prior to the U.S. filing date of the present application.

3. I alone invented the subject matter claimed in claims 19, 20, 23 and 24, which are currently pending in the present application.

4. I alone invented the subject matter that is disclosed but not claimed in the '031 patent and that has been relied upon by the Examiner in the office action mailed on December 1, 2004 as a basis for rejecting claims 19, 20, 23 and 24 in the present application.

5. The other co-inventors in the '031 patent, namely, Minoru Murata, Seiki Aoyama, and Youko Nakagawa, did not invent the subject matter that is disclosed but not claimed in the '031 patent and that has been relied upon by the Examiner in the office action mailed on December 1, 2004 as a basis for rejecting claims 19, 20, 23 and 24 in the present application.

I hereby declare that all statements made herein of my own knowledge are true and that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of any United States patent issuing on the present application.

By: Minekazu Sakai

Minekazu Sakai

Signature

February 16, 2005

Date